

SANYO Semiconductors DATA SHEET

An ON Semiconductor Company

ATP613 — General-Purpose Switching Device Applications

Features

- Reverse recovery time t_{rr}=60ns(typ.)
- Input Capacitance Ciss=350pF(typ.)
- · Halogen free compliance

- ON-resistance RDS(on)=1.55 Ω (typ.)
- · 10V drive

Specifications

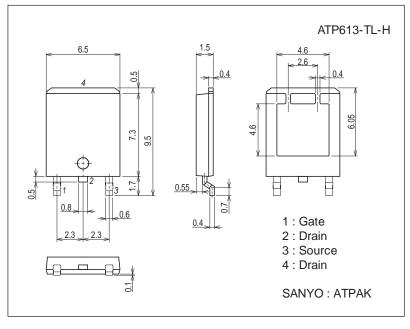
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		500	V
Gate-to-Source Voltage	VGSS		±30	V
Drain Current (DC)	ID		5.5	А
Drain Current (Pulse)	IDP	PW≤10μs, duty cycle≤1%	19	Α
Source-to-Drain Diode Forward Current (DC)	IS		5.5	А
Source-to-Drain Diode Forward Current (Pulse)	ISP	PW≤10μs, duty cycle≤1%	19	Α
Allowable Power Dissipation	PD	Tc=25°C	70	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C
Avalanche Energy (Single Pulse) *1	EAS		93	mJ
Avalanche Current *2	IAV		5.5	Α

Note: *1 VDD=99V, L=5mH, IAV=5.5A (Fig.1)

Package Dimensions

unit : mm (typ) 7057-001



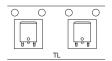
Product & Package Information

• Package : ATPAK

• JEITA, JEDEC :-

• Minimum Packing Quantity : 3,000 pcs./reel

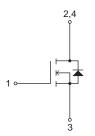
Packing Type: TL



Marking



Electrical Connection



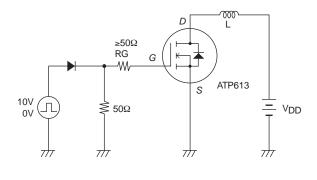
^{*2} L≤5mH, Single pulse

Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
	Syllibol	Conditions	min	typ	max	Unit
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=10mA, VGS=0V	500			V
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =400V, V _{GS} =0V			100	μΑ
Gate-to-Source Leakage Current	IGSS	V _{GS} =±30V, V _{DS} =0V			±100	nA
Cutoff Voltage	VGS(off)	V _{DS} =10V, I _D =1mA	3		5	V
Forward Transfer Admittance	yfs	V _{DS} =10V, I _D =2.75A	1.5	2.9		S
Static Drain-to-Source On-State Resistance	R _{DS} (on)	I _D =2.75A, V _G S=10V		1.55	2.0	Ω
Input Capacitance	Ciss			350		pF
Output Capacitance	Coss	V _{DS} =30V, f=1MHz		68		pF
Reverse Transfer Capacitance	Crss			15		pF
Turn-ON Delay Time	t _d (on)			14.2		ns
Rise Time	t _r	0 5: 0		46		ns
Turn-OFF Delay Time	t _d (off)	See Fig.2		37.6		ns
Fall Time	tf			20.4		ns
Total Gate Charge	Qg			13.8		nC
Gate-to-Source Charge	Qgs	V _{DS} =200V, V _{GS} =10V, I _D =5.5A		3.2		nC
Gate-to-Drain "Miller" Charge	Qgd			7.6		nC
Diode Forward Voltage	V _{SD}	I _S =5.5A, V _G S=0V		1.1	1.5	V
Reverse Recovery Time	t _{rr}	See Fig.3		60		ns
Reverse Recovery Charge	Q _{rr}	IS=5.5A, VGS=0V, di/dt=100A/μs		120		nC

Fig.1 Unclamped Inductive Switching Test Circuit

Fig.2 Switching Time Test Circuit



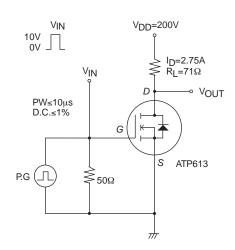
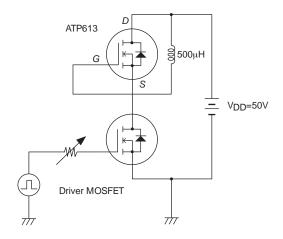
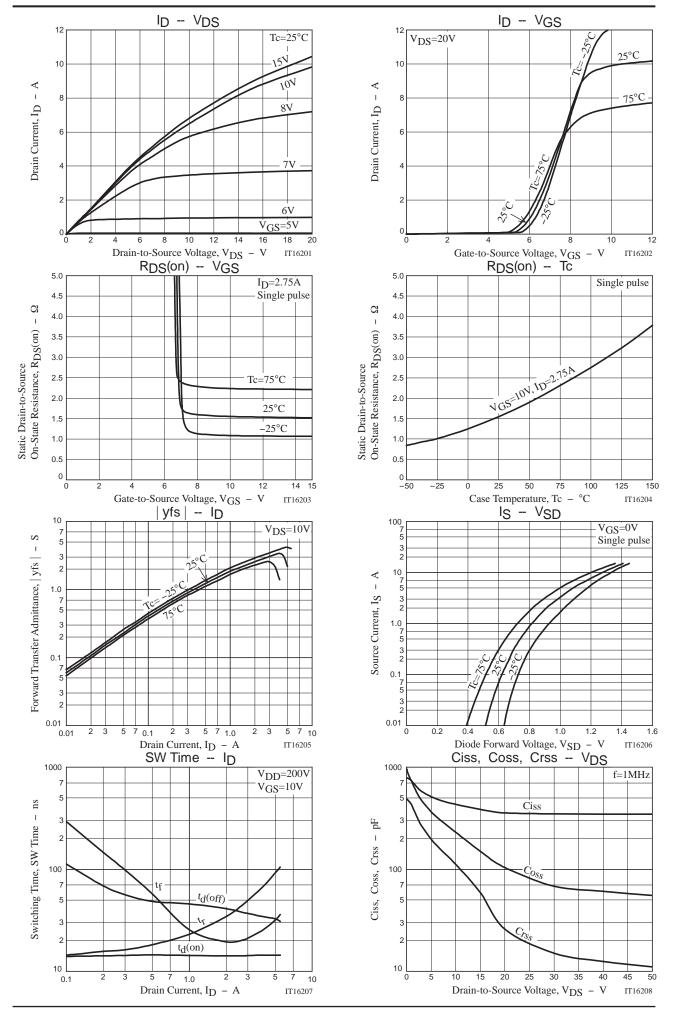


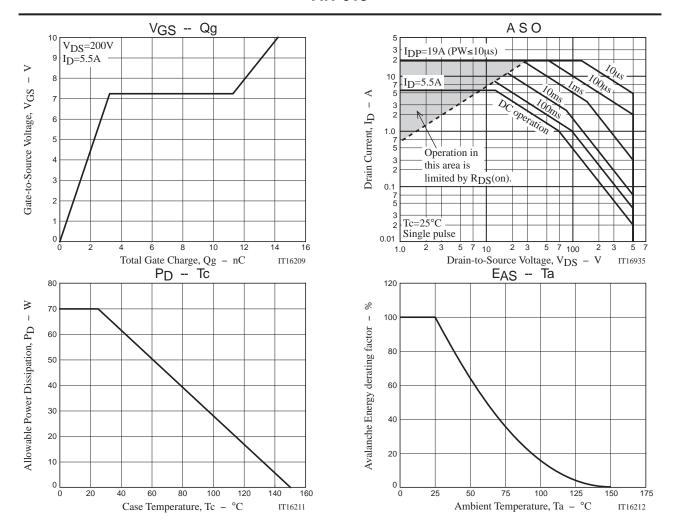
Fig.3 Reverse Recovery Time Test Circuit



Ordering Information

Device	Package	Shipping	memo	
ATP613-TL-H ATPAK		3,000pcs./reel	Pb Free and Halogen Free	



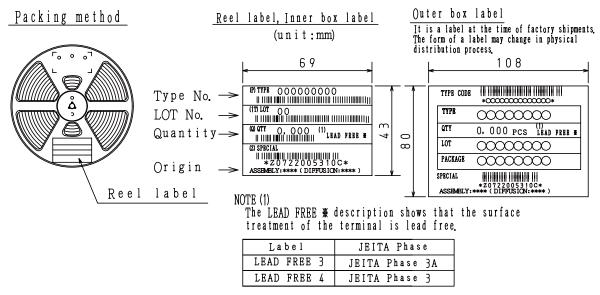


Taping Specification

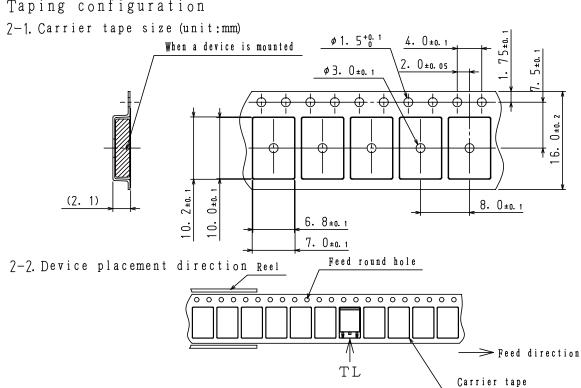
ATP613-TL-H

1. Packing Format (TL)

Package Name	Carrier Tape	pe Maximum Number of devices contained (p					Packing f	o r m a t
rackage Name	Туре	Reel	Inner box	Outer box	INNER BOX SD-C-18	OUTER BOX SD-A-18		
					1 reels contained	5 inner boxes contained		
ATPAK	ATP	3,000	3,000	15,000	Dimensions:mm (external)	Dimensions:mm (external)		
					340×340×28	355×355×165		



7. Taping configuration



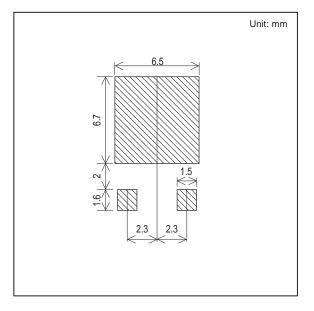
The one erectrode terminals on feed hole side····TL

Outline Drawing

ATP613-TL-H

Mass (g) Unit 0.266 mm 6 5 std 15 2 5 0 4 5 0

Land Pattern Example



Note on usage: Since the ATP613 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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